

PAD AREA
 KEEP OUT AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

备注:

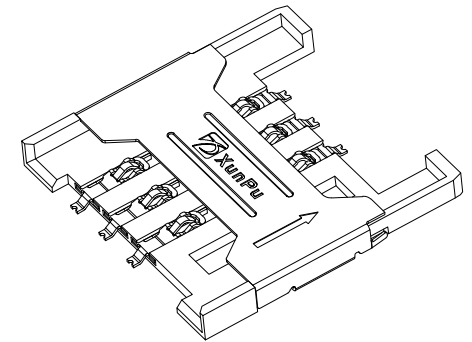
1.材质:

- 1.1胶芯:LCP UL94V-0
- 1.2端子:C2680,半金锡,触点镀金1U",雾锡80U"
- 1.3外壳:SUS201,镍底50U",焊接脚镀金1U"

2.主要特性:

- 2.1额定电流:0.5A
- 2.2接触阻抗:50MΩ MAX
- 2.3绝缘阻抗:100Ω MIN 100V DC
- 2.4耐压测试:100V AC
- 2.5沾锡性:温度235±5℃,时间5±0.5S
- 2.6单PIN正向应力:0.035KGF MIN
- 2.7使用寿命:7000次
- 2.8耐温性:烤箱测试:温度250±5℃,时间2分钟
- 2.9工作环境:温度:-30℃~+80℃;湿度:80% MAX

MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MINI SIM CARD PUSH PULL 1.5H 防撬PIN 有档
DECIMALS:	ANGLES:		PAR SIM-104
X.:±0.50	X.':±5°		DWN YE
X.X:±0.25	X.X':±3°		CHKD
X.XX:±0.12	X.XX':±1°	APVD	SCALE:1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1 REV:A